

File

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiang Dai et al.

Serial No.: 10/612,663

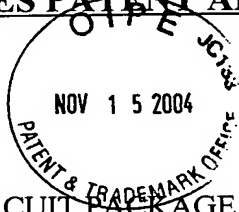
Filed: July 2, 2003

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE
HAVING A SOLDER COLUMN ARRAY

Examiner: James M. Mitchell

Group Art Unit: 2813

Docket No.: 200308566-1



AMENDMENT AND RESPONSE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Non-Final Office Action mailed August 12, 2004. Please amend the above-identified patent application as follows:

11/17/2004 MBERHE 00000002 082025 10612663

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